

## Power Die Embedding in a Power Electronics Converter

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This project, born from a partnership between Mitsubishi Electric R&D Centre Europe (MERCE) and the Ampère Laboratory in Lyon (France), consists in the enhancement of the design of conventional heat sinks, ubiquitous elements used in power electronics systems as heat dissipating units. The final goal of this project is to design, fabricate and validate a novel packaging solution that reduces the thermal resistance between the power chips (die) and the heat sink while keeping it safe to handle.

Most cases of study focus on the design of metallic heat sinks due to their easiness of shaping. Pin shaped, str

Agreements have been made towards the design of novel heat sinks using a specific class of insulating materials

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